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Intel® SSD 320 Series
(120GB, 2.5in SATA 3Gb/s, 25nm, MLC)

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Specifications

Specifications	^
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Specifications

⊖ Essentials

Capacity	120 GB
Status	End of Life
Launch Date	Q1'11
Datasheet	Link
Lithography Type	25 nm
Recommended Customer Price	N/A

⊖ Performance

Sequential Read (up to)	270 MB/s
Sequential Write (up to)	130 MB/s
Random Read (8GB Span) (up to)	38000 IOPS
Random Read (100% Span)	38000 IOPS
Random Write (8GB Span) (up to)	14000 IOPS
Random Write (100% Span)	400 IOPS
Latency - Read	75 µs
Latency - Write	90 µs
Power - Active	150 mw (MobileMark 2007 Workload), 3.0 W (64K Sequential Write)
Power - Idle	100 mw (DIPM), .7 W (Non-DIPM)

⊖ Reliability

Vibration - Operating	2.17 G_{RMS} (5-700 Hz)
Vibration - Non-Operating	3.13 G_{RMS} (5-800 Hz)
Shock (Operating and Non-Operating)	1,500 G/.5 msec
Operating Temperature Range	0°C to 70°C
Mean Time Between Failures (MTBF)	1,200,000 Hours
Uncorrectable Bit Error Rate (UBER)	1 sector per 10^{16}

⊖ Package Specifications

Components	Intel NAND Flash Memory Multi-Level Cell (MLC) Technology
Weight	up to 88 ± 2 grams
Form Factor	2.5" 7mm
Interface	SATA 3.0 3Gb/S

⊖ Advanced Technologies

Enhanced Power Loss Data Protection	Yes

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PCN/MDDS Information

911564: PCN | MDDS
911565: PCN | MDDS
911566: PCN | MDDS
911567: PCN | MDDS
913233: PCN | MDDS
918013: PCN | MDDS

Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

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